

SID

Factory: Rot am See

Article:

557

ML8

Provided:

Landwehr, Melanie

Customer:

Date:

15.12.2015



Processtechnology: B: Pinlamination

Material Text	Mat. Nr.	µm	Stackup	Process overview
---------------	----------	----	---------	------------------

A-RS Kupferfolie-018my 330x490mm	50200238	18	VS	1	
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	212		2	
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	0		3	
A-RS-FR4-ML-0.25mm-035+035-TG150-HF	50200654	35	L2	4	A01
		250			
		35	L3		
A-RS-FR4-Prepreg-7628-TG150-HF	50200643	230		5	
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	0		6	
A-RS-FR4-ML-0.25mm-035+035-TG150-HF	50200654	35	L4	7	A02
		250			
		35	L5		
A-RS-FR4-Prepreg-1080-TG150-HF	50200641	230		8	
A-RS-FR4-Prepreg-7628-TG150-HF	50200643	0		9	
A-RS-FR4-ML-0.25mm-035+035-TG150-HF	50200654	35	L6	10	A03
		250			
		35	L7		
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	212		11	
A-RS-FR4-Prepreg-2116-TG150-HF	50200642	0		12	
A-RS Kupferfolie-018my 330x490mm	50200238	18	RS	13	

Thickness after Pressing

B00:

1860 µm

Tol+:

200 µm

Tol-:

200 µm

Dmax:

2060 µm

Dmin:

1660 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

2000 µm

Tol+:

200 µm

Tol-:

200 µm

Dmax:

2200 µm

Dmin:

1800 µm

Measuring point: (05) über LM und galv.Cu; beidseitig

nominal:

1880 µm

Version 1.2.14.15

© Würth Elektronik